

In the Specification:

Page 3, amend paragraphs [0014] and [0015] and add new paragraph [0015.1] as follows.

[0014] FIG. 6 is an enlarged top plan view of a first pattern of die attach material in accordance with an embodiment of the present invention; [and]

[0015] FIG. 7 is an enlarged top plan view of a second pattern of die attach material in accordance with an embodiment of the present invention; and[.]

[0015.1] FIG. 8 is an enlarged cross-sectional view of a thin small outline package in accordance with an embodiment of the present invention.

Page 9, after paragraph [0032], add new paragraph [0032.1], as follows.

[0032.1] FIG. 8 is an enlarged cross-sectional view of a thin small outline package 50 in accordance with an embodiment of the present invention is shown. The TSOP 50 includes the integrated circuit die 34 attached to the base carrier 32, which in this case is a die paddle, with the extended adhesive material layer 36. The integrated circuit die 34 is electrically connected to the pins 18 of a leadframe with wires 20 in a known manner, such as by wirebonding the wires 20 to pads on the die 34 and to the leadframe pins 18. The die 34, base carrier 32, and wires 20 are encapsulated with an encapsulant, such as with the molded plastic 22.